

The TIG™780-10 products are the high-efficiency heat dissipation ones for the fillings between the electronic components and the heat dissipation fins. They serve to moisten the contact surface sufficiently so as to form an interface of extremely low thermal impedance. Consequently, the heat dissipation efficiency is far superior to that offered by others.



导热膏

TIG™780-10产品是呈膏状的高效散热产品，填充在电子组件和散热片之间，它能充分润湿接触表面，从而形成一个非常低的热阻介面，散热效率比其它类散热产品要优越很多。

For Lowest Thermal Resistance :

- › **0.15°C-in² /W** thermal resistance
- › One component paste like interface material, never dry.
- › Thermal compound formulated to maximize the heat transfer.
- › Outstanding electrical insulation properties and will not harden on long exposure to elevated temperatures.
- › Non-toxic and environmentally safe

Applications Include:

- › Semiconductor cases and heat sinks.
- › Power resistors and chassis, thermostats and mating surfaces, and thermoelectric cooling devices.
- › CPU's and GPU's.
- › Automatic dispensing and screen-printing.

最小熱阻系列:

- › **0.15°C-in² /W** 熱阻
- › 一种类似导热界面材料的粘胶,不会干燥。
- › 为热传导化学物,可以最大化半导体块和散热器之间的热传导。
- › 卓越电绝缘,长时间暴露在高温环境下也不会硬化。
- › 环保无毒。

適用於:

- › 半导体块和散热器。
- › 电源电阻器与底座之间,温度调节器与装配表面,热电冷却装置等。
- › 高性能中央处理器及显卡处理器。
- › 自动化操作和丝网印刷。

Typical Properties of TIG™780-10 TIG™780-10系列特性表

Product Name(產品名稱)	TIG™780-10	Test Method(測試方法)
Color(顏色)	White (白)	Visual(目視)
Construction & Composition (結構&成分)	Metal oxide filled silicone oil (金屬氧化物矽油)	
Viscosity (黏度)	1000K cps @.25°C	Brookfield RVF,#7
Specific Gravity(比重)	2.2 g/cm ³	
Continuous Use Temp (使用溫度範圍)	-49°F to 392°F / -45°C to 200°C	*****
Evaporation (揮發率)	0.23% / 200°C @24hrs	*****
Thermal Conductivity (導熱率)	1.0 W/mK	ASTM D5470
Thermal Impedance (熱阻抗)	0.15°C-in ² /W @ 50 psi(344 KPa)	ASTM D5469

包裝 Package

TIG™780 series is available in 1kg (pint container), 3kg (quart container), and 10kg (gallon container) or custom packaged in syringes for automated applications.

TIG™780 系列可分裝於1公斤(品脫罐)，3公斤(夸脫罐)，10公斤(加侖罐)，客戶也可裝入注射筒以便自動化操作。